

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#3

In re application of:

FUNAMOTO et al.

Serial No.: 09/395,179

Filed: September 14, 1999

For: PACKAGE FOR ELECTRONIC COMPONENT, LID MATERIAL FOR  
PACKAGE LID, AND PRODUCTION METHOD FOR LID MATERIAL



Group Art Unit: 1725

Examiner:

**INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. §1.97**

Commissioner for Patents  
Washington, D. C. 20231

June 26, 2000

TO: 1725 PAT. ROOM

JUN 27 2000

RECEIVED

Sir:

In compliance with applicants' duty of disclosure under 37 C.F.R. §1.56, the following is material information of which applicants are aware, and which is relevant to the above-identified application:

- (1) Japanese Patent publication, 06053341, February 25, 1994;
- (2) Japanese Patent publication, 09199622, July 31, 1997;
- (3) Japanese Patent publication, 63-51661, March 4, 1988.

A copy of the above-cited references are attached hereto.

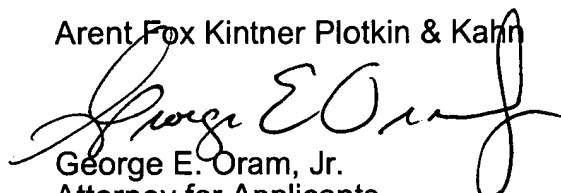
The undersigned hereby certifies that each item of information contained in the attached Information Disclosure Statement was cited in a communication from the Japanese Patent Office dated March 7, 2000 in a counterpart foreign application which is

not more than three (3) months prior to the date of filing of this Information Disclosure Statement.

Should any fees be necessary in connection with the filing of this paper, please charge them to Counsel's Deposit Account No. 01-2300.

Respectfully submitted,

Arent Fox Kintner Plotkin & Kahn



George E. Oram, Jr.  
Attorney for Applicants  
Registration No. 27,931

Atty. Docket No. 107459-09002

1050 Connecticut Ave., NW, Suite 600  
Washington, D.C. 20036-5339  
(202) 857-6000

GEO:sah

Enclosures: PTO-1449  
Documents (3)